



## **INTERMOLECULAR LAUNCHES PLATFORM TO REDEFINE SEMICONDUCTOR R&D SPEED AND ROI**

*Tempus HPC Platform Delivers Chip Industry's First Dedicated R&D Infrastructure For Dramatically Faster Results, Reduced Cost and Risk*

SAN JOSE, Calif. — July 16, 2007 — Intermolecular, Inc. today officially launched its fully integrated combinatorial semiconductor R&D platform — a set of systems and methods that radically accelerate discovery, and integration of new materials, new process technologies and new device structures for chipmakers, materials suppliers and equipment manufacturers.

The company's Tempus™ High-Productivity Combinatorial™ (HPC) platform enables customers to maximize their R&D return on investment through economical high-speed development, integration and electrical testing of a previously inconceivable number of alternative solution sets.

HPC™ technology is derived from technologies whose speed and effectiveness have been demonstrated for more than 15 years in the energy, pharmaceutical, biotechnology and other materials discovery-driven industries. Intermolecular leads the semiconductor industry in developing and commercializing HPC technologies. The company's intellectual property portfolio includes access to more than 700 patents, granted or pending.

Launching the Tempus HPC platform on the eve of SEMICON West 2007, Intermolecular founder and CEO David Lazovsky noted that the inefficiencies of traditional approaches to R&D are introducing economic barriers for many companies, and straining their ability to sustain the pace of innovation necessary to remain competitive.

"Economic considerations are playing a larger role in the semiconductor industry's R&D landscape than technical synergies," Lazovsky said. "The technical challenges not only remain, they are growing exponentially. For example, new materials integration is now a larger factor in driving IC performance than dimensional scaling. The IC industry is putting the Periodic Table to work to enable next-generation electronics. However, new processes and integration methods are required that can take several years to develop. Intermolecular directly addresses these challenges by making available to our customers a complementary technology platform, Tempus, which speeds their R&D learning rate by orders of magnitude compared to conventional R&D methods."

The Tempus HPC Platform of products and services currently includes a Fluids Line for applications including self-assembly, surface preparations and cleans processes and electroless deposition, and a Physical Vapor Deposition Line for applications including non-volatile memory, high-*k*/metal gate and advanced interconnect.

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Customers have leveraged these HPC technologies in several ways — via collaborative development programs (CDPs) with Intermolecular's multidisciplinary team, by purchasing Tempus systems, or through licensing IP developed and qualified by Intermolecular. Customers achieve streamlined development and reduced time-to-market — critical competitive advantages that are increasingly difficult and costly to achieve through traditional R&D approaches. The company's customers include leading chipmakers, materials suppliers and equipment manufacturers in North America, Europe and Asia.

"The replacement cycle of consumer electronics is driving substantially shorter semiconductor innovation cycles," said George Scalise, president of the Semiconductor Industry Association (SIA) and a member of Intermolecular's board of directors. "We need to investigate and pursue new methods to improve semiconductor R&D efficiency. Intermolecular's Tempus HPC platform gives our semiconductor R&D community a powerful new tool to change the fundamental economics of bringing new product generations to market."

A more detailed description of the Tempus HPC platform and information about customer projects are available at [www.intermolecular.com](http://www.intermolecular.com).

#### **About Intermolecular**

Intermolecular, Inc. delivers High Productivity Combinatorial™ (HPC) technology products and services that enable customers to maximize semiconductor R&D ROI. The company's Tempus™ HPC Platform offers chipmakers, materials suppliers and equipment manufacturers integrated processing, characterization and informatics systems that exponentially accelerate learning in materials discovery, process development and IC device integration.

Customers apply Intermolecular's technologies in their R&D projects through collaborative development programs (CDPs) with Intermolecular's multidisciplinary team, purchase of Tempus systems, or licensing of IP developed and qualified by Intermolecular. By leveraging HPC technologies to quickly develop, integrate and electrically test multiple alternative solutions, at minimum cost and risk, customers obtain unique IP and time-to-market advantage.

Founded in 2004, Intermolecular is based in San Jose, California. For more information, visit [www.intermolecular.com](http://www.intermolecular.com).

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